

Final Product/Process Change Notification Document #: FPCN20419X

Issue Date: 18 August 2015

Title of Change:	Transfer of 5x5 to 7x7 mm body size Punch type QFN with Matte lead finish to Amkor Philippines (P1) due to Amkor Korea (K1) Closure in wk16 2016.				
Proposed first ship date:	25 November 2015 or Earlier upon customer approval				
Contact information:	Contact your local ON Semiconductor Sales Office or <sarah.sanico@onsemi.com></sarah.sanico@onsemi.com>				
Samples:	Contact your local ON Semiconductor Sales Office				
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <phine.guevarra@onsemi.com></phine.guevarra@onsemi.com>				
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>				
Change Part Identification:	Affected products will be identified by datecode following the Assembly location code of new site as 'L'.				
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other				
Change Sub-Category(s): □ Datasheet/Product Doc change ☑ Manufacturing Site Change/Addition □ Material Change □ Shipping/Packaging/Marking □ Manufacturing Process Change □ Product specific change □ Other:					
Sites Affected: ☐ All site(s) ☐ not ap	pplicable ON Semiconductor site(s): Sexternal Foundry/Subcon site(s) Amkor Technology Korea K1 Amkor Technology Philippines P1				
Description and Purpose:					
Amkor is closing the Korea K1 Plant per type of package. Assembly manufacturing operations for all Leadframe products now assembled in K1 will need to move to Philippines, P1 Plant. K1 bill of materials and process will be supported in P1. Summarize on the table below are the packages for transfer and its equivalent bill of materials:					
DOM for Motto Tip Local finish	ATV4	ATD1	Domorks		
BOM for Matte Tin Lead finish	ATK1	ATP1	Remarks		
Leadframe	CuAg CRM1085A	CuAg CRM1085A	No Change		
Epoxy Mold compound	G700	G700	No Change No Change		
Wiola compound	1 3700	3,00	140 Change		

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Reliability Data Summary:

Qualification Vehicle 20674-003

32 QFN (Punch) 7x7

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Test	Specification	Conditions	Interval	Results	
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	504, 1008 hrs	0/240	
HTSL	JESD22-A103	Ta= 150°C	504, 1008 hrs	0/219	
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/238	
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/239	
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240	
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C		0/717	
SD	JSTD002	Ta = 245C, 10 sec		0/45	

For more details on the qualification and reliability result, please contact ONSEMI Sales Office.

Electrical Characteristic Summary:

Electrical characteristics are not impacted

List of Affected Standard Parts:

Part Number	Qualification Vehicle
ADT7462ACPZ-REEL	20674-003
AMIS-49250-XTD	20674-003
AMIS-49250-XTP	20674-003

List of Affected Customer Specific Parts:

NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN & CPN info will be available to affected customers only by clicking the "Custom PCN for Selected Company Button" in the Document Analysis page of PCMS/PCN Alert.

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